CMOS Omnipolar High Sensitivity Micropower Hall Switch

1. Features

Micropower consumption for battery powered applications

Omnipolar, output switches with absolute value of North or South pole from magnet

Operation down to 2.5V

High sensitivity for direct reed switch replacement applications

Chopper stabilized amplifier stage



2. Description

The JTM90248 Omnipolar Hall effect sensor IC is fabricated from mixed signal CMOS technology. It incorporates advanced chopper-stabilization techniques to provide accurate and stable magnetic switch points.

The circuit design provides an internally controlled clocking m echanism to cycle power to the Hall element and analog signal processing circuits. This serves to place the h igh current-consuming portions of the circu it into a "Sleep" m ode. Periodically the device is "A wakened" by this internal logic and the magnetic f lux from the Hall element is evaluated against the predefined thresholds. If the f lux density is above or below the Bop/Brp thresholds then the output transistor is driven to change s tates accordingly. While in the "Sleep" cy cle the output transistor is latched in its previous state. The design has been optimized for service in applications requiring extended operating lifetime in battery powered systems.

The output transistor of the JTM90248 will be latched on (Bop) in the pre sence of a sufficiently strong South or North m agnetic field facing the m arked side of the package. The output will be latched off (Brp) in the absence of a magnetic field.

3. Applications

Solid state switch

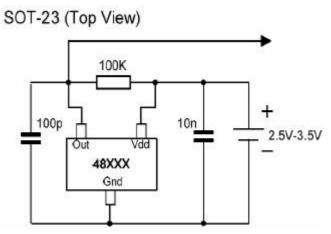
Handheld Wireless Handset Awake Switch

Lid close sensor for battery powered devices

Magnet proximity sensor for reed switch replacem ent in low duty cycle applications

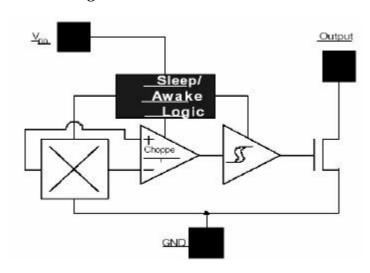
4. Typical Application Circuit

Eastera's pole-independent sensing technique allows for operation with either a north pole or south pole magnet orientation, enhancing the manufacturability of the device. The state-of-the-art technology provides the same output polarity for either pole face.

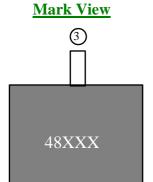


It is strongly recommended that an external bypass capacitor be connected (in close proximity to the Hall sensor) between the supply and ground of the device to reduce both external noise and noise generated by the chopper-stabilization technique. This is especially true due to the relatively high impedance of battery supplies.

5. Functional Block Diagram



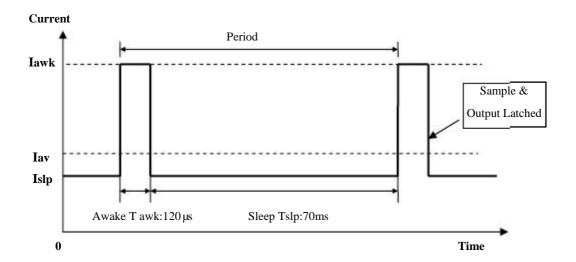
6. Pinning



Pin Description

NAME	NO	STATUS	DESCRIPTION
Vdd	1	Р	Power Supply
Out	2	О	output
Gnd	3	Р	IC Ground

7. Internal Timing Circuit



8. Absolute Maximum Ratings

Parameter	Symbol	Value	Units
Supply Voltage(operating)	$V_{ m DD}$	5	V
Supply Current	I_{DD}	5	mA
Output Voltage	V_{OUT}	5	V
Output Curent	Іоит	5	mA
Operating Temperature Range	TA	-40 to 85	°C
Storage Temperature Rang	Ts	-50 to 150	°C
ESD Sensitivity	-	4000	V

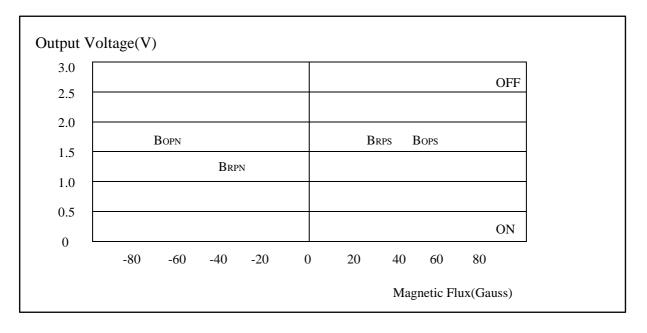
Exceeding the absolute maximum ratings may cause permanent damage. Exposure to absolute-maximum rated conditions for extended periods may affect device reliability.

9. DC Electrical Characteristics

DC Operating Parameters: $T_A = 25^{\circ}C$, $V_{DD}=2.75V$.

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Operating voltage	V_{DD}	Operating	2.5	3	5.5	V
Supply current	I_{DD}	Average		7		μΑ
Output Current	Iout				1.0	mA
Saturation Voltage	V_{SAT}	=Iout 1mA			0.4 V	
Awake mode time	Taw	Operating		175		μS
Sleep mode time	Tsl	Operating			70	mS

10. Magnetic Characteristics



Operating Parameters: $T_A = 25 \,^{\circ}\text{C}$, $V_{DD} = 2.75 \, V_{DC}$.

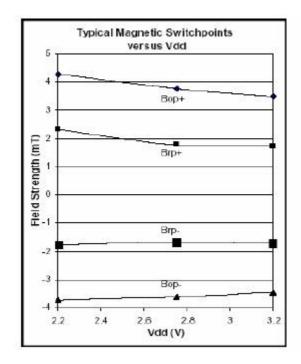
PARAMETER	Symbol	Min	Type	Max	Units
Operating Point	Bop	ı	+/-38	+/-60	Gs
Release Point	Brp	+/-5	+/-21	-	Gs
Hysteresis	Bhys	-	17	-	Gs

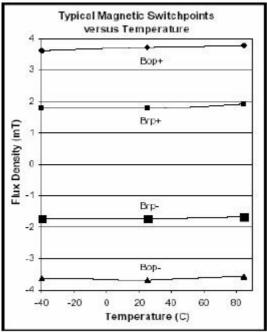
11. ESD Protection

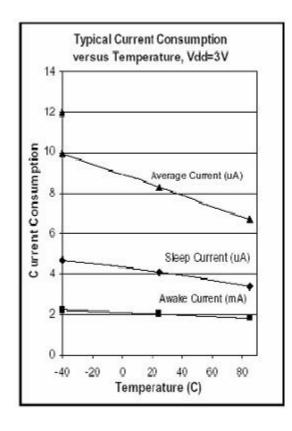
Human Body Model (HBM) tests according to: Mil. Std. 883F method 3015.7

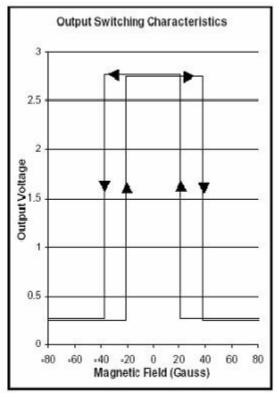
Parameter	Symbol	Limit Values		Unit	Notes
		Min	Max		
ESD Voltage	$\mathbf{V}_{ ext{ESD}}$		± 4	kV	

12. Performance Characteristics









13. Unique Features

CMOS Hall IC Technology

The chopper stabilized am plifier uses switc hed capacitor techniques to elim inate the amplifier offset voltage, which, in bipolar devices, is a major source of temperature sensitive drift. CMOS makes this advanced technique possible. The CMOS chip is also much smaller than a bipolar chip, allowing very sophisticated circuitry to be placed in less space. The small chip size also contributes to lower physical stress and less power consumption.

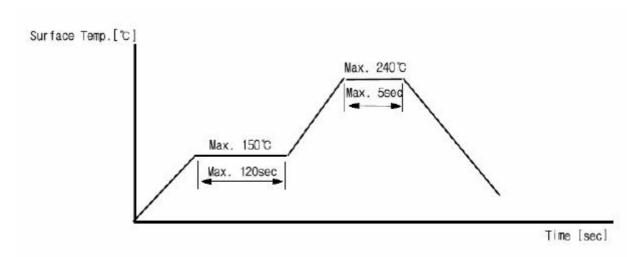
Installation Comments

Consider temperature coefficients of Hall IC and magnetics, as well as air gap and life time variations. Observe temperature lim its during wave soldering. T ypical IR solder -reflow profile:

No Rapid Heating and Cooling.

Recommended Preheating for max. 2minutes at 150°C

Recommended Reflowing for max. 5seconds at 240°C

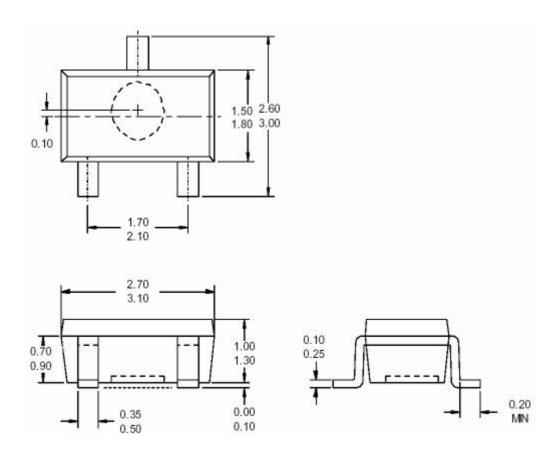


14. ESD Precautions

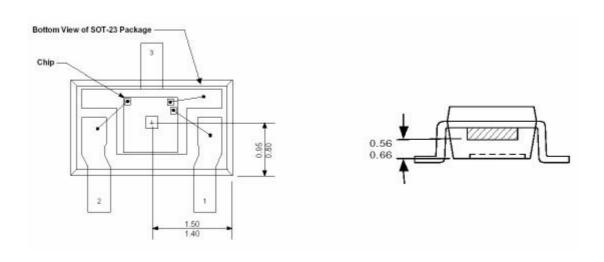
Electronic semiconductor products are sensitiv e to Electro Static D ischarge (ESD). Always observe Electro Static Discharg e control procedures whenever handling semiconductor products.

15. Package Information

15.1 SOT-23 Package Physical Characteristics



SOT-23 Package Hall Location



15.2 TO-92 Package Physical Characteristics

